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PMP9334

PMP9334 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB	1		PMP9334	Any	Printed Circuit Board	
C1	1	10uF	C5750X7S2A106M	TDK	CAP, CERM, 10uF, 100V, +/-20%, X7S, 2220	2220
C105	1	680pF	C0603C681K5RACTU	Kemet	CAP, CERM, 680 pF, 50 V, +/- 10%, X7R, 0603	0603
C111	1	470uF	EMVY350ATR471MKE0S	Nippon Chemi-Con	CAP, AL, 470uF, 35V, +/-20%, 0.07 ohm, SMD	KE0
C121	1	0.33uF	GRM21BR71E334KA01L	MuRata	CAP, CERM, 0.33uF, 25V, +/-10%, X7R, 0805	0805
CC1, CSS	2	0.47uF	C0603C474K4RACTU	Kemet	CAP, CERM, 0.47 µF, 16 V, +/- 10%, X7R, 0603	0603
CC2	1	330pF	C0603C331K5RACTU	Kemet	CAP, CERM, 330 pF, 50 V, +/- 10%, X7R, 0603	0603
CIN	1	10uF	C2012X5R1E106K125AB	TDK	CAP, CERM, 10 µF, 25 V, +/- 10%, X5R, 0805	0805
CIN1, CIN2, CIN3, CIN4	4	0.047uF	C1812V473KDRACTU	Kemet	CAP, CERM, 0.047 µF, 1000 V, +/- 10%, X7R, 1812	1812
CISO1, CISO2	2	1000pF	VJ1210A102JXGAT5Z	Vishay-Vitramon	CAP, CERM, 1000 pF, 1000 V, +/- 5%, C0G/NP0, 1210	1210
CVCC	1	1uF	GRM188R61E105KA12D	MuRata	CAP, CERM, 1 µF, 25 V, +/- 10%, X5R, 0603	0603
D1	1	15V	CMZ5929B TR13	Central Semiconductor	Diode, Zener, 15 V, 1.5 W, SMA	SMA
D2	1	5.6V	CMZ5919B TR13	Central Semiconductor	Diode, Zener, 5.6 V, 1.5 W, SMA	SMA
D3	1	18V	CMZ5931B LEAD FREE	Central Semiconductor	Diode, Zener, 18 V, 900 mW, SMA	SMA
D4	1	200V	MBRB20200CTT4G	ON Semiconductor	Diode, Schottky, 200V, 20A, DDPAK	DDPAK
D105	1	1.25V	1N4148W-7-F	Diodes Inc.	Diode, Ultrafast, 100V, 0.15A, SOD-123	SOD-123
J1, J2	2		6091	Keystone	Standard Banana Jack, Insulated, Red	6091
J3, J4	2		6092	Keystone	Standard Banana Jack, Insulated, Black	6092
Q100	1	1000V	FQD2N100TM	Fairchild Semiconductor	MOSFET, N-CH, 1000 V, 1.6 A, DPAK	DPAK
Q101	1	40 V	CMST2222A TR	Central Semiconductor	Transistor, NPN, 40 V, 0.6 A, SOT-323	SOT-323
Q102	1	1000V	STP8NK100Z	STMicroelectronics	MOSFET, N-CH, 1000 V, 6.5 A, TO-220AB	TO-220AB
R1, R2, R3	3	200k	CRCW0805200KJNEA	Vishay-Dale	RES, 200k ohm, 5%, 0.125W, 0805	0805
R4, R5, R6	3	1.0Meg	CRCW08051M00JNEA	Vishay-Dale	RES, 1.0Meg ohm, 5%, 0.125W, 0805	0805
R106	1	4.99k	CRCW12064K99FKEA	Vishay-Dale	RES, 4.99k ohm, 1%, 0.25W, 1206	1206
R108	1	499	CRCW0603499RFKEA	Vishay-Dale	RES, 499, 1%, 0.1 W, 0603	0603
R110	1	18.7k	RG1608P-1872-B-T5	Susumu Co Ltd	RES, 18.7k ohm, 0.1%, 0.1W, 0603	0603
R111	1	1.50k	CRCW06031K50FKEA	Vishay-Dale	RES, 1.50 k, 1%, 0.1 W, 0603	0603
R112	1	16	CRCW060316R0JNEA	Vishay-Dale	RES, 16 ohm, 5%, 0.1W, 0603	0603
R114	1	215k	CRCW0603215KFKEA	Vishay-Dale	RES, 215 k, 1%, 0.1 W, 0603	0603
R115, R116	2	0.5	CSRN2010FKR500	Stackpole Electronics Inc	RES, 0.5, 1%, 1 W, 2010	2010
R117	1	100	CRCW1206100RFKEA	Vishay-Dale	RES, 100 ohm, 1%, 0.25W, 1206	1206
R121, REN	2	300k	RC0603FR-07300KL	Yageo America	RES, 300k ohm, 1%, 0.1W, 0603	0603
RC1	1	1.87k	CRCW06031K87FKEA	Vishay-Dale	RES, 1.87 k, 1%, 0.1 W, 0603	0603
T100	1	3mH	G094215LF	GCI Tech	Transformer, 3mH	
U1	1		LM5022MM	Texas Instruments	60V Low Side Controller for Boost and SEPIC	MUB10A
C112	0	470uF	EMVY350ATR471MKE0S	Nippon Chemi-Con	CAP, AL, 470uF, 35V, +/-20%, 0.07 ohm, SMD	KE0
D103	0	24V	1SMB5934BT3G	ON Semiconductor	Diode, Zener, 24V, 550mW, SMB	SMB
Z1	0	120V	SMAJ120A	Littelfuse	Diode, TVS, Uni, 120V, 400W, SMA	SMA

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